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Oct. 26, 2001

Tammy Shyen



GP 2813  
#8(me)  
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MH

Attorney Docket No. 000265

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**Inventor:** L. Richard Carley

**Serial No.:** 09/583,386

**Filing Date:** May 30, 2000

**Examiner:** Erik Kielin

**Art Unit:** 2813

**Entitled:** MANUFACTURING OF MEMS STRUCTURE IN SEALED CAVITY USING DRY-RELEASE MEMS DEVICE ENCAPSULATION

**RESPONSE AND AMENDMENT**

Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

This communication is being filed in response to the Notice of Non-Compliant Amendment dated October 19, 2001 in the above-referenced U.S. patent application.

The Applicant requests the entry of the following Amendments:

**In the Specification:**

- On page 3, please delete the third full paragraph and replace it with the following paragraph:

Figures 1A and 1B show a top view and a side cross-sectional view respectively of the silicon CMOS wafer used as the base of the MEMS micro-encapsulated structure.

- On page 3, please delete the fourth full paragraph and replace it with the following paragraph:

Figures 2A and 2B show a top view and a cross-sectional view respectively of the wafer of the Figure 1A with a sacrificial layer deposited thereon.

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DUPLICATE OF PAPER NO. 7, AMENDMENT B, 1/4/02